



COPY OF PAPERS
ORIGINALLY FILED

#6/92823
2382
J.D.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Lamson et al.

Docket No.: TI-31189

Serial No.: 09/989,263

Examiner: Maldonado, J.

Filed: 11/19/01

Art Unit: 2823

For: LOW CAPACITANCE COUPLING WIRE BONDED
SEMICONDUCTOR DEVICE

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, DC 20231

Dear Sir:

RECEIVED
SEP 12 2002
TC 2800 MAIL ROOM

MAILING CERTIFICATE	
I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, DC 20231.	
Date	8-27-02
<i>Marianna Smith</i> Marianna Smith	

Please make the references listed on the enclosed PTO-1449 of record under 37 C.F.R. 1.56, 1.97, and 1.98 in the patent application identified above. They were cited in a corresponding European patent application. Copies of the listed references and European search report are enclosed.

Respectfully submitted,

Michael K. Skrehot
Attorney for Applicants
Reg. No. 36,682

Texas Instruments Incorporated
P. O. Box 655474, MS 3999
Dallas, Texas 75265
(972) 917-5653
FAX: (972)917-4418
(972)917-4417